

600584



Jiangsu Changjiang Electronics Technology Co., Ltd.

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QFII

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12

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125,000

120,000

9.5	FC	84,080
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		<b>120,000</b>

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/ /		2013
/		234,962,406 A
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/		
		Integrated Circuit, IC
		IC IC
FC/		Flip Chip
BGA		Ball Grid Array
FCBGA		Flip Chip Ball Grid Array
Flip Chip on L/F		Flip Chip on Lead/Fram

FCLGA		Flip Chip Land Grid Array
Bumping		FC UBM Cr Ni Ti Ti/w Cu Au
MEMS		Micro Electro Mechanical systems
Yole Développement		
WLCSP		Wafer Level Chip Scale Packaging CSP
TSV		Through-Silicon Via
SiP		System in Package

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.....	2
.....	5
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Jiangsu Changjiang Electronics Technology Co.,Ltd.

78

85,313.361

600584

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2011

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2012

FC

FC

QFII

2013 11 28

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234,962,406

234,962,406

12

12

125,000

120,000



2013 11 27



LED

2005 3,800 2012 8,558.6 2012  
59.26%  
2005 985.78 2012 2,158.45

AP

2 FC

1,035.67 2006 511.6 2012  
2008  
2010

I/O

FC

I/O

FC

FC

FC

Yole Développement

2012

FC

200

2018

350

28nm IC

DDR

2.5D/3D IC

interposer

FC

FC

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2011

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0.8

BGA

PGA

CSP

MCM

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2011 4

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FC

BGA

CSP

MCP

SiP

3D

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2012 28

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22

12

28

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**5**

116,700

12,828

2010	2011	2012	2013	9
46.47%	57.50%	62.98%	65.58%	

**3**

			2010	2011	2012
2013	1-9		9,032.43	10,015.91	
15,725.51	13,486.27				

	853,133,610	
138,927,411	16.28%	
		234,962,406
234,962,406		
1,088,096,016		12.77%

" 9.5 FC "

2013 9 30 66.53%  
65.58% 0.63 0.48

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5.32 /

A

16.28%

5%

2008



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2

3

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2

3

70%

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**3**

2010      2012

2012	0.00	1,041.00	-
2011	0.00	6,731.71	-
2010	5,118.80	20,771.21	24.64%
			<b>9,514.64</b>
			<b>53.80%</b>

30%

2011      2012

2011

2012

**2013 ~2015**

2013 -2015

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1

2  
-2015 )

( 2013

3

20%

4

2

**2013 12 6**